



| REVISIONS |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SYM | ECN | DESCRIPTION | DATE | APPROVED |  |  |
|  |  | SEE SHEET1 |  |  |  |  |


RECOMMENDED PCB FOOTPRINT (OPTION 1)



SECTION A-A

[^0]| $\begin{gathered} \text { UNLESS OTHERWWE SPECIFIED } \\ \text { TOLERANCES } \\ \text { U.S. } \end{gathered}$ |  | APPROVAL |  | $\begin{array}{\|c\|} \hline \text { DATE } \\ \hline \text { Aug. } 19,2021 \\ \hline \end{array}$ | Amphenol |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | DRAWN $\mathrm{Kelem.Y} \mathrm{Yang}$ |  |  |  |  |  |  |  |  |  |
|  |  | CHECKED |  |  |  |  |  |  |  |  |  |
|  |  | TITLE |  |  |  |  |  |  |  |  |  |
|  |  |  |  |  |  |  |  |  |  |  |  |  |  |  |  |
| For Material | FINISHES | DRAWING FILE DRAWING \DDR\DDR504XXXXXXXH |  |  | DDR | 288P R | R/LR DIMM C |  | CONNECTOR |  |  |
| Remove s | EDGES | DRAWING \DDR\DDR504XXXXXXXH <br> angle of projection |  |  |  |  | - |  |  |  |  |
|  |  | ANGLE OF PROJECTION$\circledast \square$ |  |  |  |  | SIZE DRAWING NO. <br> A3 C DDR5-04-X-X-X-XxX-X-H |  |  |  |  |  | REV. |
| U.S. | INeHES |  |  |  |  |  |  |  |  |  |  |  | 5 |
| (METRC) | (MM) |  |  |  | SCALE | NONE |  | SHEET | 5 | OF | 7 |





1. MATERIAL:
1.1 HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, COLOR:OPTION.
1.1 HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, COLOR:OPTION.
1.2 LATCH: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0. COLOR: OPTION.
1.3 TERMINAL: COPPER ALLOY.
1.4 BOARDLOCK: COPPER ALLOY
1.5 METAL CLIP: SUS.
2. FINISH:
2.1 TERMINAL:
2.1.1 CONTACT AREA: SELECTED GOLD PLATING;
2.1.2 SOLDERING AREA: MATTE TIN PLATING $100 u^{\prime \prime}$ THICKNESS MIN

UNDER PLATING: NICKEL PLATING 50u" THICKNESS MIN. UNLESS OTHERWISE SPECIFIED
2.2 BOARDLOCK:
2.2.1 $10 u^{\prime \prime}$ MIN LEAD FREE MATTE TIN OVER $50 u^{\prime \prime}$ MIN NICKEL UNDERPLATED OVERALL
3. ELELTRICAL CHARACTERISTICS
3.2 INSULATION RESISTANCE.1MO MAX
3.3 DIELECTRIC WTSSTANDE:MM MIN. 500 ADC.
3.4 LOW LEVEL CONTACT RESISTANCE: 500 VAC AT SEA LEVEL.

INITIALL4OR MAX.
FINAL:THE
THAL:THE CHANGE IN LLCR BETWEEN THE READING AFTER STRESS AND
mechanica intial reading siall not exceed $20 \mathrm{~m} \Omega$ max
4. MECHANICAL CHARACTERISTICS
4.1 CONTACT RETENTION FORCE:300gF MIN/PER PIN
4.2 DURABILITY:25 CYCLES.

UNMATING FORCE: 19.77N MIN.
5. RELIABILITY AND OTHER CHARACTERISTICS:
5.1 SOLDERABILITY -LEAD FREE: JESD22-B102; CONDITION C. 8 HOURS $\pm 15$ MINUTES STEAM PRECONDITION.

5 HZ @ $0.01 \mathrm{~g} \mathrm{~g}^{2} 2 / \mathrm{HZ}$ TO 20 HZ @ $0.02 \mathrm{~g}^{\circ} 2 / \mathrm{HZ}$ (SLOPE UP), 20 HZ TO 500 HZ @ 0.02g^2/HZ (FLAT) INPUT ACCELERATION IS 3.13 g RMS
5.3 CYCLIC TEMPERATURE AND HUMIDITY: PER EIA-364-31, METHOD III WITHOUT CONDITIONING,

INITIAL MEASUREMENTS, COLD SHOCK AND VIBRATION.
5.4 THERMAL SHOCK: PASSED PER EIA-364-32, METHOD A, TABLE 2, TEST CONDITION 1 ,
$-55^{\circ} \mathrm{C}$ TO $85^{\circ} \mathrm{C}$. PERFORM 5 CYCLES IN MATED CONDITION.
5.5 MECHANICAL SHOCK: EIA-364-27, TEST CONDITION E,
5.6 OPERATING TEMPERATURE: - $55^{\circ} \mathrm{C}$ TO $85^{\circ} \mathrm{C}$.
6. HALOGEN-FREE COMPLIANT PRODUCT. MEET AMPHENOL SPEC \# S-SN-004
$\overline{\text { DOUBLE DATA RATE } 5 \text { SERIES }}$
XX: APPLICATION TYPE
04: SMT,288P, R/LR DIMM CONNECTOR
X: HOUSING COLOR
BLACK
2: NATURAL (IVORY)
YELLOW
bLUE
X: LATCH COLOR
1: BLACK
DDR $5 \times \times \times \times \times \times \mathrm{x} \times \mathrm{x}$

2: NATURAL (IVORY)

X: CUSTOMER CODE OPTION:


X: PACKING AND MYLAR OPTIONS
T: SOFT TRAY
H: HARD TRAY PACKAGE, WITH MYLAR " $X$ " $=40 \mathrm{MM}$
J: HARD TRAY PACKAGE, WITH MYLAR "X"=70MM
K: HARD TRAY PACKAGE, WITHOUT MYLAR
M: HARD TRAY PACKAGE, WITH MYLAR "X" $=90 \mathrm{MM}$

See sequence number table
X: CONTACT PLATED
0: GOLD FLASH
1: $15 u^{\prime \prime}$ Au ON CONTACT AREA
2: $30 u^{\prime \prime} \mathrm{Au}$ ON CONTACT AREA
3: $\quad 15 u^{\prime \prime}$ MIN GXT
4: $\quad 30 u^{\prime \prime}$ MIN GXT
5: $15 u^{\prime \prime}$ Au ON CONTACT AREA AND $90 u^{\prime \prime}$ Ni MIN ON UNDERPLATING
6: $30 u^{\prime \prime}$ Au ON CONTACT AREA AND $90 u^{\prime \prime}$ Ni MIN ON UNDERPLATING
8: $\quad 18 u^{\prime \prime}$ AU ON CONTACT AREA



[^0]:    NoTES:

    1. MATERIAL: HIPS, BLACK
    2. QUANTITY:32PCS/TRAY
